

Special Issue

CFD Applications in Heat Transfer Research and Simulation

Message from the Guest Editor

This Special Issue on “CFD Applications in Heat Transfer Research and Simulation” aims to provide the latest significant advances in the applications of computational fluid dynamics in heat transfer. Topics include, but are not limited to:

- CFD fundamentals;
- CFD applications in electronics cooling;
- CFD applications in heat exchangers;
- CFD applications in power generation, combustion, and rotating machinery;
- CFD simulations of devices and processes for heat transfer enhancement.

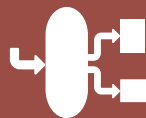
Guest Editor

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Deadline for manuscript submissions

closed (20 December 2023)



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